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(71) Applicant: SONY CORP

(72) Inventor: MIYAMORI YUUICHI

(54) METHOD AND APPARATUS FOR MANUFACTURING ELECTRONIC DEVICE

(57) Abstract:

PROBLEM TO BE SOLVED: To avoid shape deformation such as dishing or recess when a metal layer is buried in trenches formed in an insulation film and it is planarized by the chemical-mechanical polishing method.

SOLUTION: A metal layer 7 is deposited by the plating method and the metal layer 7 is removed by the chemical-mechanical polishing method. The deposition of the metal layer 7 by the plating method and

the removal of the metal layer 7 by the chemical-mechanical polishing method may be alternately repeated.

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